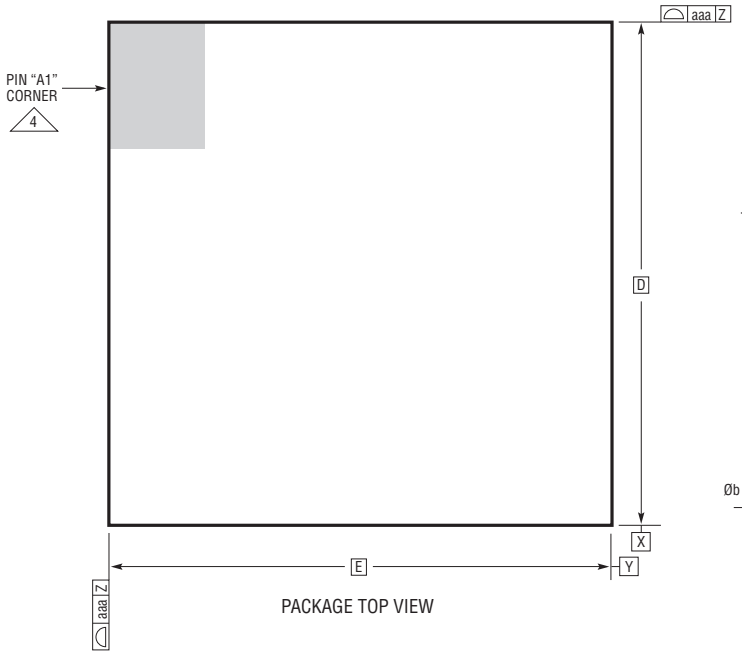
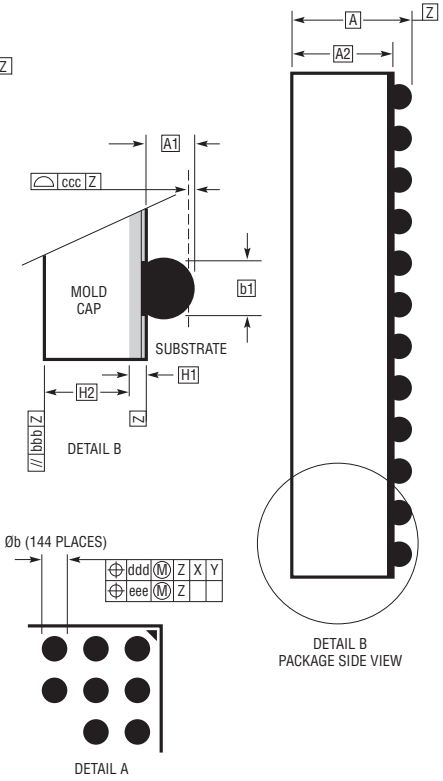
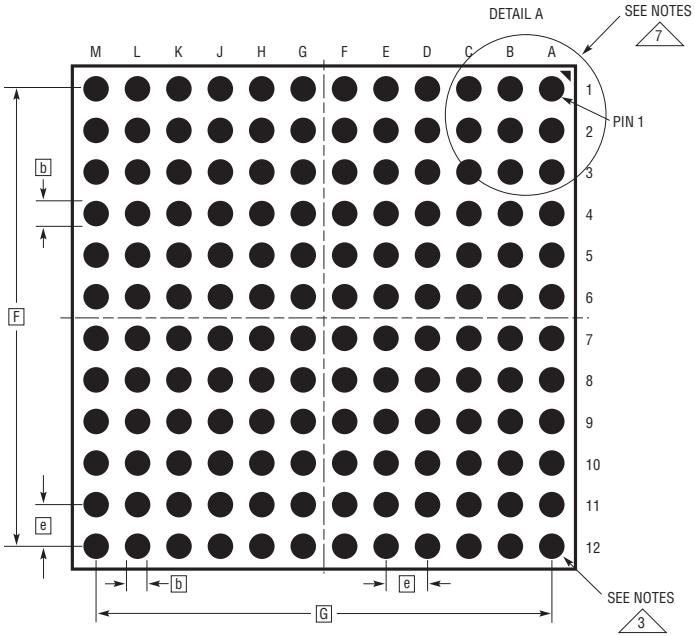
BGA Package
144-Lead (16mm × 16mm × 2.51mm)
(Reference LTC DWG # 05-08-1503 Rev A)

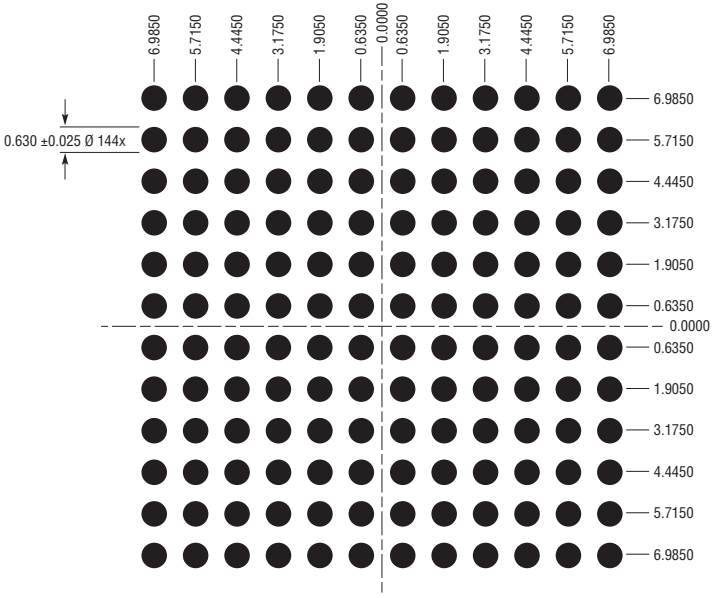


PACKAGE TOP VIEW





PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	2.31	2.51	2.71	
A1	0.50	0.60	0.70	
A2	1.81	1.91	2.01	
b	0.60	0.75	0.90	
b1	0.60	0.63	0.66	
D		16.00		
E		16.00		
e		1.27		
F		13.97		
G		13.97		
H1	0.36	0.41	0.46	
H2	1.45	1.50	1.55	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	
TOTAL NUMBER OF BALLS: 144				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994

2. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING NOT TO SCALE

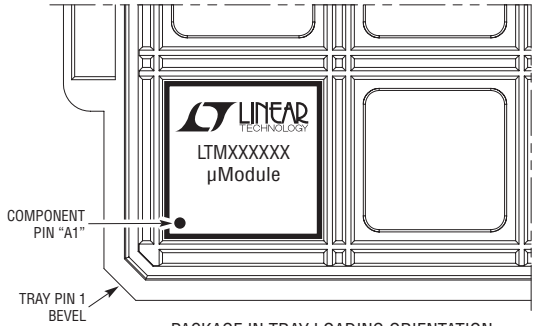
3 BALL DESIGNATION PER JESD MS-028 AND JEP95

4 DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu

7 ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 144 1015 REV A